Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HP ProCurve 8206zl Switch Base System (J9475A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm 9(mandatory) & 9(optional) in product, 1 in power supply (Mandatory) & 1 power supply (Optional)	10 (Mandatory) 10(Optional)
Batteries	All types including standard alkaline and lithium coin or button style batteries BR2032	1 (Mandatory) 1(Optional)
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries Nil	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps Nil	0
Cathode Ray Tubes (CRT)	Nil	0
Capacitors / condensers (Containing PCB/PCT)	2 on power supply (another power supply optional)	2
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords	Power cord and console serial cable	2
Gas Discharge Lamps	Nil	0
Plastics containing Brominated Flame Retardants	Nil	0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos	Nil	0
Components, parts and materials containing refractory ceramic fibers		0

Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx driver (standard)	T10, T15 & T20
Small adjustable wrench	5mm
Wire cutter	Medium

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Check chassis for zl modules installation at chassis front side.
2. If zl modules are installed, go to Step 3, else go to Step 5.
3. Unfasten the Captive screws on all the zl modules.
4. Disassemble zl modules from chassis.
5. Unfasten the Captive screws & remove the Blank bulkheads, Blank Management module, Mangement & Fabric modules from the chassis
6. Remove the TRS screw (T20) that fasten the System support module
7. Remove the System support module from the chassis
8. Disassemble the Front flap from the chassis
9. Remove all the screws that fasten the Power distribution PCA's (4 & 6 slots) onto the Card guides
10. Remove the 2 Power distribution PCA's along with the isolators
11. Remove the screws that fasten the Grounding lug to the chassis rear side
12. Remove the Grounding lug
13. Unfasten the captive screws on the Fan tray assy
14. Remove the Fan tray assy from the chassis
15. Unfasten the captive screws of the Power supply unit / PS Blank assy from the chassis
16. Remove Power supply unit/PS Blank assy.
17. Remove screws that fasten the Power supply tray on to the chassis
18. Remove the PS tray assy.
19. Remove sheetmetal parts and accessory (LED) PCA.
20. Remove screws that fasten the Rear cover plate on to the chassis
21. Remove the Rear cover plate
22. Remove all the screws that fasten the Backplane PCA onto the Card guides
23. Remove Backplane PCA (last item).

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).